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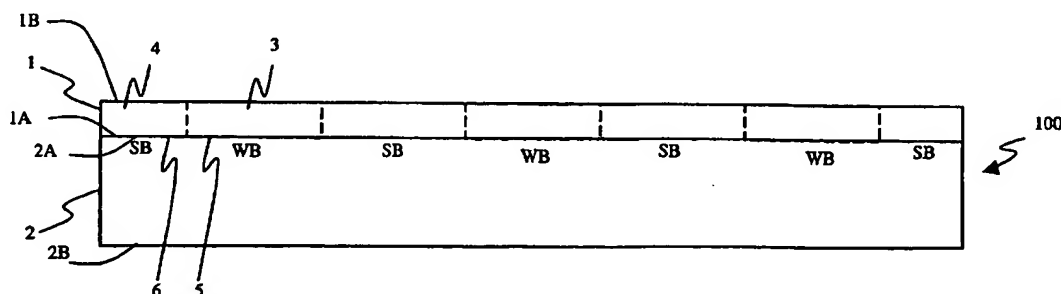
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(54) Title: THIN FILMS AND PRODUCTION METHODS THEREOF



(57) Abstract: A layered structure generally includes a first layer suitable for having a useful element formed therein or thereon

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Minimum documentation searched (classification system followed by classification symbols)
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Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

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Category *	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
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☒ Patent family members are listed in annex.

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INTERNATIONAL SEARCH REPORT

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C.(Continuation) DOCUMENTS CONSIDERED TO BE RELEVANT

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